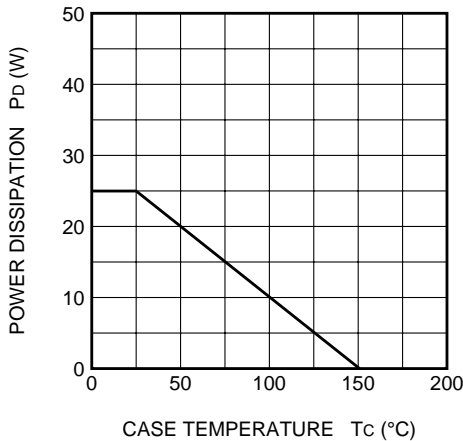


ELECTRICAL CHARACTERISTICS (Tch = 25°C)

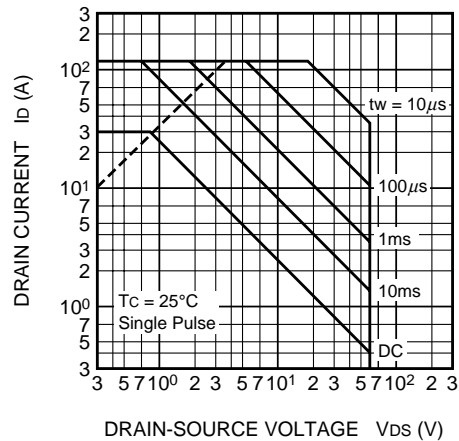
Symbol	Parameter	Test conditions	Limits			Unit
			Min.	Typ.	Max.	
V(BR)DSS	Drain-source breakdown voltage	Id = 1mA, VGS = 0V	60	—	—	V
IGSS	Gate-source leakage current	VGS = ±20V, VDS = 0V	—	—	±0.1	μA
IDSS	Drain-source leakage current	VDS = 60V, VGS = 0V	—	—	0.1	mA
VGS(th)	Gate-source threshold voltage	Id = 1mA, VDS = 10V	1.0	1.5	2.0	V
rDS(ON)	Drain-source on-state resistance	Id = 15A, VGS = 10V	—	25	30	mΩ
rDS(ON)	Drain-source on-state resistance	Id = 15A, VGS = 4V	—	31	38	mΩ
VDS(ON)	Drain-source on-state voltage	Id = 15A, VGS = 10V	—	0.38	0.45	V
yfs	Forward transfer admittance	Id = 15A, VDS = 10V	—	28	—	S
Ciss	Input capacitance	VDS = 10V, VGS = 0V, f = 1MHz	—	1800	—	pF
Coss	Output capacitance		—	340	—	pF
Crss	Reverse transfer capacitance		—	180	—	pF
td(on)	Turn-on delay time	VDD = 30V, ID = 15A, VGS = 10V, RGEN = RGS = 50Ω	—	17	—	ns
tr	Rise time		—	46	—	ns
td(off)	Turn-off delay time		—	120	—	ns
tf	Fall time		—	95	—	ns
VSD	Source-drain voltage	IS = 15A, VGS = 0V	—	1.0	1.5	V
Rth(ch-c)	Thermal resistance	Channel to case	—	—	5.00	°C/W
trr	Reverse recovery time	IS = 30A, dis/dt = -100A/μs	—	60	—	ns

PERFORMANCE CURVES

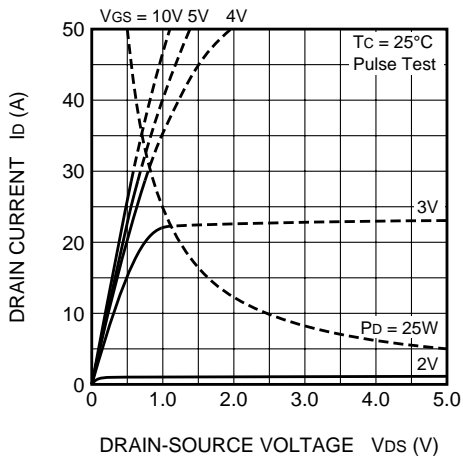
POWER DISSIPATION DERATING CURVE



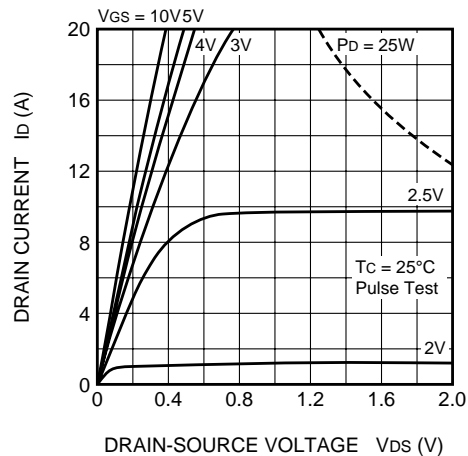
MAXIMUM SAFE OPERATING AREA



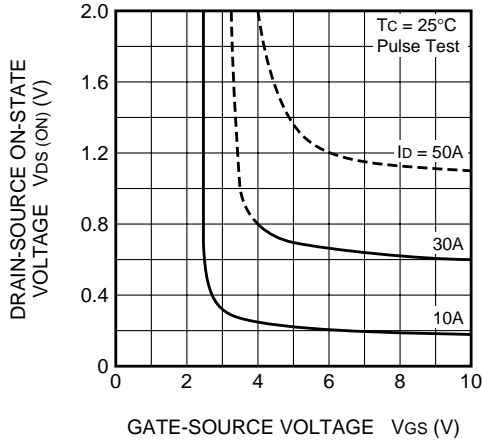
OUTPUT CHARACTERISTICS (TYPICAL)



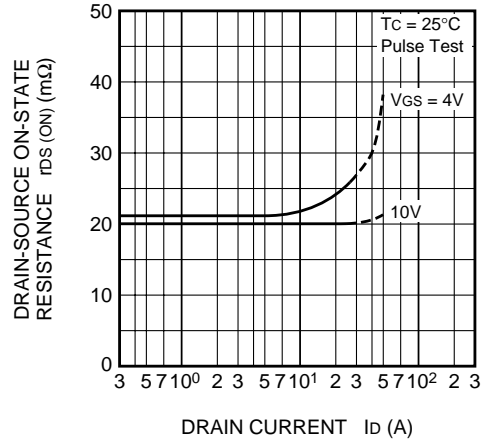
OUTPUT CHARACTERISTICS (TYPICAL)



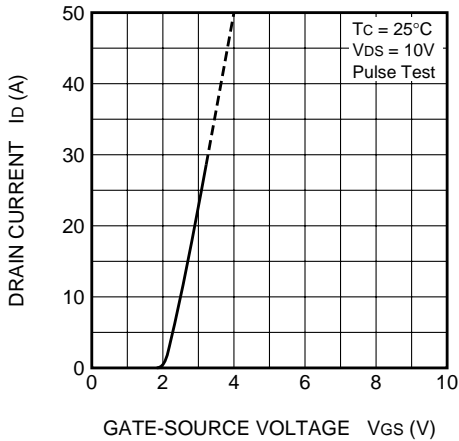
ON-STATE VOLTAGE VS. GATE-SOURCE VOLTAGE (TYPICAL)



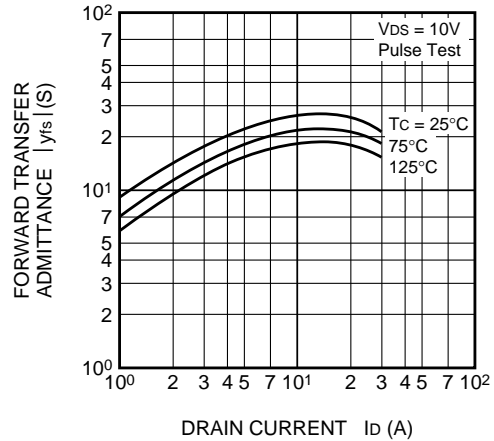
ON-STATE RESISTANCE VS. DRAIN CURRENT (TYPICAL)



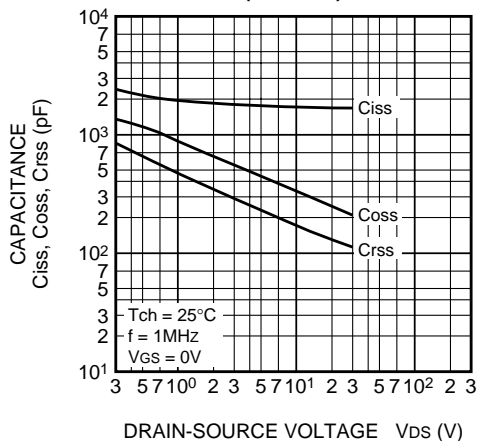
TRANSFER CHARACTERISTICS (TYPICAL)



FORWARD TRANSFER ADMITTANCE VS. DRAIN CURRENT (TYPICAL)



CAPACITANCE VS. DRAIN-SOURCE VOLTAGE (TYPICAL)



SWITCHING CHARACTERISTICS (TYPICAL)

